### 3.2x1.6mm SMD CHIP LED LAMP

Part Number: KPTD-3216SECK-J3 Hyper Red

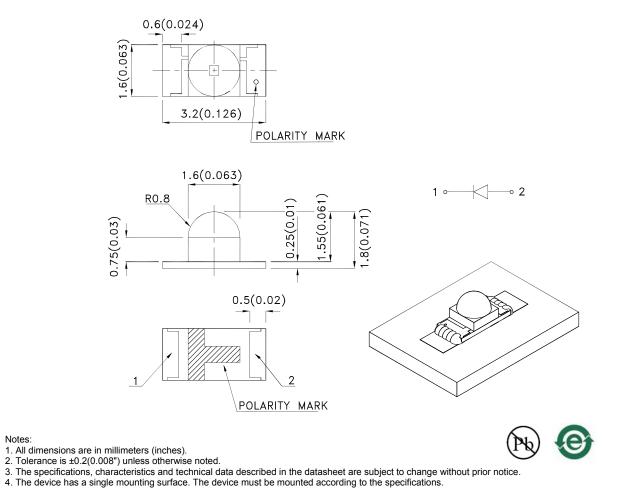
#### **Features**

- 3.2mmX1.6mm SMT LED, 1.8mm thickness.
- Low power consumption.
- Ideal for backlight and indicator.
- Various colors and lens types available.
- Package: 2000pcs / reel .
- Moisture sensitivity level : level 3.
- RoHS compliant.

#### Description

The Hyper Red device is based on light emitting diode chip made from AlGaInP.

#### **Package Dimensions**



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### Soloction Guido

Selection Guide					
Part No.	Dice	Lens Type	lv (mcd) [2] @ 20mA		Viewing Angle [1]
			Min.	Тур.	201/2
KPTD-3216SECK-J3	Hyper Red (AlColnD)	Water Clear	4200	7500	- 35°
	Hyper Red (AlGaInP)		*1600	*2500	

Notes:

1.  $\theta$ 1/2 is the angle from optical centerline where the luminous intensity is 1/2 of the optical peak value.

Luminous intensity/ luminous Flux: +/-15%.
\* Luminous intensity value is traceable to the CIE127-2007 compliant national standards.

#### Electrical / Optical Characteristics at TA=25°C

Symbol	Parameter	Device	Тур.	Max.	Units	Test Conditions
λpeak	Peak Wavelength	Hyper Red	640		nm	I⊧=20mA
λD [1]	Dominant Wavelength	Hyper Red	625		nm	I⊧=20mA
Δλ1/2	Spectral Line Half-width	Hyper Red	20		nm	I⊧=20mA
С	Capacitance	Hyper Red	27		pF	VF=0V;f=1MHz
Vf [2]	Forward Voltage	Hyper Red	2.2	2.8	V	I⊧=20mA
IR	Reverse Current	Hyper Red		10	uA	VR=5V

Notes:

1.Wavelength: +/-1nm.

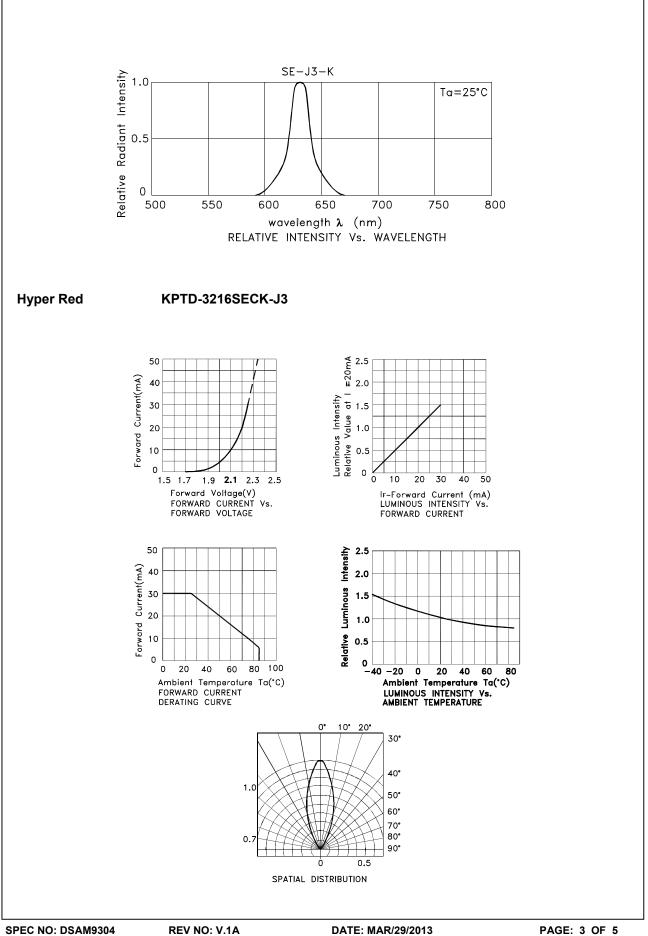
2. Forward Voltage: +/-0.1V.

3. Wavelength value is traceable to the CIE127-2007 compliant national standards.

#### Absolute Maximum Ratings at TA=25°C

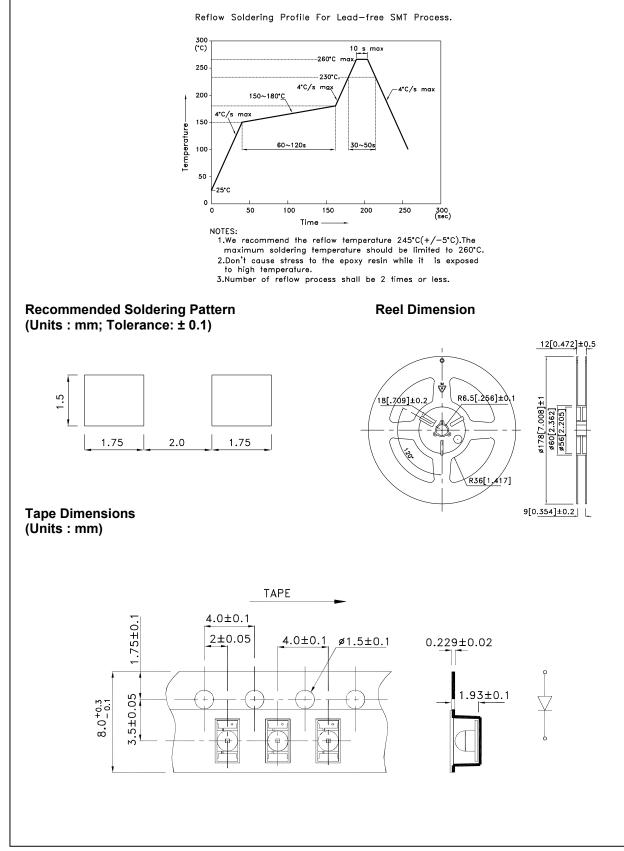
Parameter	Hyper Red	Units	
Power dissipation	84	mW	
DC Forward Current	30	mA	
Peak Forward Current [1]	150	mA	
Reverse Voltage	5	V	
Operating Temperature	-40°C To +85°C		
Storage Temperature	-40°C To +85°C		

Note: 1. 1/10 Duty Cycle, 0.1ms Pulse Width.



### KPTD-3216SECK-J3

Reflow soldering is recommended and the soldering profile is shown below. Other soldering methods are not recommended as they might cause damage to the product.



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